



Final Product/Process Change Notification

Document #:FPCN23658ZP

Issue Date:15 Feb 2022

Title of Change:	Wafer fab transfer to onsemi Gresham, Oregon USA from onsemi Fab2, Oudenaarde, Belgium related to Fab2 sale
Proposed Changed Material First Ship Date:	01 Sep 2022 or earlier if approved by customer
Current Material Last Order Date:	31 Mar 2022 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	31 Aug 2022 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local onsemi Sales Office or Kevin.Mathews@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	01 Feb 2022
PPAP Availability Date:	31 Mar 2022
Additional Reliability Data:	Contact your local onsemi Sales Office or Catherine.DeKeukeleire@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .
Change Category	
Category	Type of Change
Design	Design Change in Routing
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.
Process - Assembly	Change of mold compound, Change of leadframe base material, Change of product marking
Description and Purpose: After the announcement on February 03rd, 2020 of the sale of Fab2, onsemi pursues the transfer of relevant products. Before Last Order Date above: customers must provide Last-Time-Buy volume for products that will be transferred to manufacture the bridge-build quantity in the current facility (fab2) before the selling. After the last order date above: the orders will be placed on the new part number (replacement part) or on the receiving fab (products with the same part number). Last Delivery Date above: subject to a commercial agreement, onsemi may extend the deliveries outside the 06 months windows which is the proposed date of implementation in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements but after depletion of inventory of the current material. However, such extended delivery conditions could be subject to an extension of the date code currently at 12 months	

	Before Change Description	After Change Description
Wafer Fab Site	onsemi, Oudenaarde, Belgium	onsemi, Gresham, Oregon, USA
Wafer Size	150 mm	200 mm
Equipment	150 mm Production Line	200 mm Production Line
Mold Compound	G600	G700LS
Leadframe	Cu	Cu Roughened
Other Changes	Original Die	Additional 15k GDRV resistor to GND on chip

	From	To
Product marking change	Line 1: 887001 Line 1: 887100 Line 1: 887103 Line 1: 887104 Line 1: 887105 Line 1: 887300 Line 1: 887302 Line 1: 898031	Line 1: 887001G Line 1: 887100G Line 1: 887103G Line 1: 887104G Line 1: 887105G Line 1: 887300G Line 1: 887302G Line 1: 898031G

Reason / Motivation for Change:	Source/Supply/Capacity Changes
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	<p>The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded.</p> <p>No anticipated impacts.</p>

Sites Affected:	
onsemi Sites	External Foundry/Subcon Sites
onsemi Carmona, Philippines	None
onsemi Oudenaarde, Belgium	
onsemi, Gresham United States	

Marking of Parts/ Traceability of Change:	Traceability guaranteed by datecode
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Reliability Data Summary: NOTE: AEC-1pager is attached. <i>To view attachments:</i> 1. Download pdf copy of the PCN to your computer 2. Open the downloaded pdf copy of the PCN 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field 4. Then click on the attached file



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Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NCV898031D1R2G	NA	NCV887100D1R2G
NCV887302D1R2G	NA	NCV887100D1R2G
NCV887300D1R2G	NA	NCV887100D1R2G
NCV887105D1R2G	NA	NCV887100D1R2G
NCV887104D1R2G	NA	NCV887100D1R2G
NCV887103D1R2G	NA	NCV887100D1R2G
NCV887100D1R2G	NA	NCV887100D1R2G
NCV887001D1R2G	NA	NCV887100D1R2G